engineering proceedings

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Editorial

Statement of Peer Review †

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In submitting conference proceedings of the 2024 IEEE 4th International Conference on Electronic Communications, Internet of Things and Big Data (IEEE ICEIB 2024) to *Engineering Proceedings*, the volume editors of the proceedings certify to the publisher that all papers published in this volume have been subjected to peer review administered by the volume editors. Reviews were conducted by expert referees to the professional and scientific standards expected of a proceedings journal.

- Type of peer review: single-blind;
- Conference submission management system: http://www.iceib.asia/;
- Number of submissions sent for review: 183;
- Number of submissions accepted: 80;
- Acceptance rate: 0.437;
- Average number of reviews per paper: 2;
- Total number of reviewers involved: 50;
- Any additional information on the review process: please refer to Figure 1.

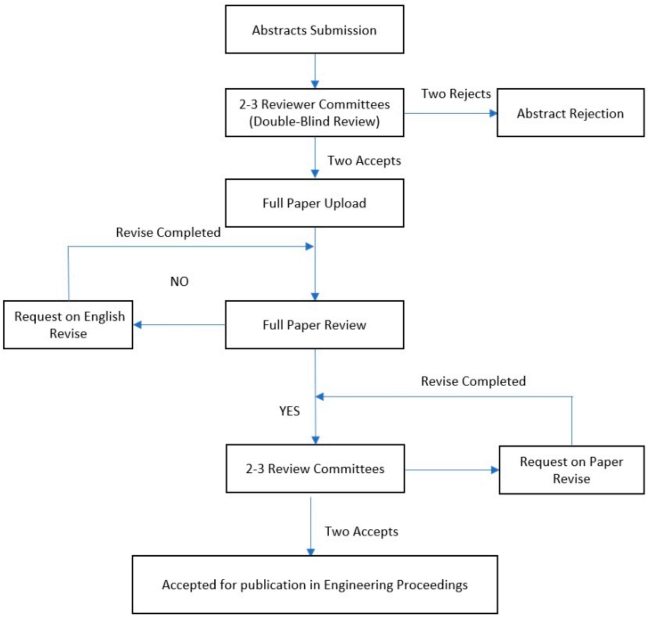

Figure 1. Review process for conference proceedings of the 4th IEEE International Conference on Electronic Communications, Internet of Things and Big Data 2024 (IEEE ICEIB 2024).

check for updates

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